

Title (en)
COPPER ALLOY

Title (de)
KUPFERLEGIERUNG

Title (fr)
ALLIAGE DE CUIVRE

Publication
EP 1873266 A1 20080102 (EN)

Application
EP 06728554 A 20060228

Priority

- JP 2006303738 W 20060228
- JP 2005055144 A 20050228
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Abstract (en)
A copper alloy, containing: Ni and/or Si, and at least one or more of B, Al, As, Hf, Zr, Cr, Ti, C, Fe, P, In, Sb, Mn, Ta, V, S, O, N, Misch metal (MM), Co, and Be, with a balance being Cu and inevitable impurities; the copper alloy having a precipitate X composed of Ni and Si; and a precipitate Y composed of Ni and/or Si, and at least one or more of B, Al, As, Hf, Zr, Cr, Ti, C, Fe, P, In, Sb, Mn, Ta, V, S, O, N, Misch metal (MM), Co, and Be, in which a grain diameter of the precipitate Y is 0.01 to 2 μm .

IPC 8 full level
C22C 9/06 (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP US)
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Cited by
RU2677902C1; EP2256219A4; EP2221391A4; US10056166B2; US9460825B2

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DE FR

DOCDB simple family (publication)
EP 1873266 A1 20080102; EP 1873266 A4 20100728; EP 1873266 B1 20120425; CN 101166840 A 20080423; CN 101166840 B 20120718; US 2008047634 A1 20080228; US 2011186187 A1 20110804; WO 2006093140 A1 20060908

DOCDB simple family (application)
EP 06728554 A 20060228; CN 200680006379 A 20060228; JP 2006303738 W 20060228; US 201113083874 A 20110411; US 84607407 A 20070828